PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Atsushi KOMIYA	06/27/2008
Hiroyuki HONDA	06/27/2008
Takuya FUJIKAWA	06/27/2008
Akihiio MOROFUJI	06/27/2008

RECEIVING PARTY DATA

Name:	TOYO SEIKAN KAISHA, LTD.
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PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11575435

OP $40.00 11575435

CORRESPONDENCE DATA

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NAME OF SUBMITTER:	Sadao Kinashi

Total Attachments: 1

Docket No. _____ **Westerman, Hattori, Daniels & Adrian, LLP**

U.S. ASSIGNMENT

IN CONSIDERATION of the sum of One Dollar ($1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter ASSIGNOR) by

(Insert ASSIGNEE's Name(s) Address(es))

TOYO SEIKAN KAISHA, LTD.

1-3-1, Uchisaiwaicho, Chiyoda-ku Tokyo 1008522

(hereinafter ASSIGNEE), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled

(Title of Invention)

FLAT CONTAINER COMPRISING THERMOPLASTIC RESIN AND METHOD FOR MOLDING THE SAME

(*If the assignment is being filed after the filing of the application, this section must be completed)

for which application for Letters Patent of the United States was executed on even date herewith unless otherwise indicated below:

* filed on **March 16, 2007** Serial No. **11/575,435**

(**Westerman, Hattori, Daniels & Adrian, LLP** is hereby authorized to insert the series code, serial number and/or filing date hereon, when known)

and all Letters Patent of the United States to be obtained therefore on said application or any continuation, divisional, substitute, reissue or reexamination thereof for the full term or terms for which the same may be granted.

The ASSIGNOR agrees to execute all papers necessary in connection with the application and any continuation, divisional, reissue or reexamination applications thereof and also to execute separate assignments in connection with such applications as the ASSIGNEE may deem necessary or expedient.

The ASSIGNOR agrees to execute all papers necessary in connection with any interference, litigation, or other legal proceeding which may be declared concerning this application or any continuation, divisional, reissue or reexamination thereof or Letters Patent or reissue patent issued thereon and to cooperate with the ASSIGNEE in every way possible in obtaining and producing evidence and proceeding with such interference, litigation, or other legal proceeding.

IN WITNESS WHEREOF, the undersigned inventor(s) has (have) affixed his/her/their signature(s).

(Signatures)

Atsushi Komiya.	**Atsushi KOMIYA**	June 27, 2008.
(Signature)	(Type Name)	(Date)
Hiroyuki Honda	**Hiroyuki HONDA**	June 27, 2008
(Signature)	(Type Name)	(Date)
Takuya Fujikawa	**Takuya FUJIKAWA**	June 27. 2008
(Signature)	(Type Name)	(Date)
Akihiko Morofuji	**Akihiko MOROFUJI**	June 27, 2008
(Signature)	(Type Name)	(Date)
(Signature)	(Type Name)	(Date)
(Signature)	(Type Name)	(Date)

NO LEGALIZATION REQUIRED